



Material Content Data Sheet



Sales Product Name		BTS6143D		Issued		31. July 2018		
MA#		MA000913726						
Package		PG-TO252-5-11		Weight*		357.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.157	0.32	0.32	3238	3238
chip_2	inorganic material	silicon	7440-21-3	4.425	1.24	1.24	12382	12382
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		172	
	non noble metal	iron	7439-89-6	0.205	0.06		572	
	non noble metal	copper	7440-50-8	204.243	57.16	57.24	571459	572203
	non noble metal	aluminium	7429-90-5	1.982	0.55	0.55	5547	5547
wire	organic material	carbon black	1333-86-4	1.366	0.38		3821	
	plastics	epoxy resin	-	23.902	6.69		66875	
encapsulation	inorganic material	silicondioxide	60676-86-0	111.313	31.14	38.21	311446	382142
	non noble metal	tin	7440-31-5	5.072	1.42	1.42	14193	14193
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.076	0.02	0.02	213	214
solder	non noble metal	tin	7440-31-5	0.069	0.02		194	
	noble metal	silver	7440-22-4	0.087	0.02		242	
	non noble metal	lead	7439-92-1	3.305	0.92	0.96	9246	9682
	plastics	Polyimide	26023-21-2	0.143	0.04	0.04	399	399
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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